

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A semiconductor light emitting device comprising a metallic support plate; a light-reflective reflector mounted on the support plate and formed with a hole upwardly diverging; a semiconductor light emitting element mounted on the support plate within the hole of the reflector, the light emitting element having a first electrode electrically connected to the support plate; a first wiring conductor electrically connected to the support plate; a second wiring conductor electrically connected to a second electrode of the light emitting element; and a heat-resistible plastic encapsulant formed of opaque or semi-transparent resin for sealing at least an outer periphery of the reflector, an upper surface of the support plate, each inner end of the first and second wiring conductors, wherein said plastic encapsulant is provide with an opening through which the hole and an upper surface of the reflector are visible from outside of said plastic encapsulant.
2. (previously presented) The semiconductor light emitting device of claim 1, further comprising a lens formed of light-transmittable or transparent resin for covering upper surfaces of the reflector and plastic encapsulant.
3. (previously presented) The semiconductor light emitting device of claim 2, further comprising a light-transmittable or

transparent cover for covering a hole of the reflector.

4. (previously presented) The semiconductor light emitting device of claim 1, wherein the support plate is formed of a metallic material having the thermal conductivity equal to or more than 190 kcal/mh°C.

5. (currently amended) The semiconductor light emitting device of claim ~~±~~ 21, wherein the lens is formed of a resin which has the melting point lower than that of the plastic encapsulant.

6-12 (canceled).

13. (currently amended) A semiconductor light emitting device comprising a support plate; a light-reflective and electrically conductive reflector mounted on the support plate and formed with a hole upwardly diverging; and a semiconductor light emitting element mounted on the support plate within the hole of the reflector;

wherein the reflector has a ledge connected to a wiring conductor to electrically connect the light emitting element and wiring conductor through the ledge.

14. (original) The semiconductor light emitting device of claim 13, wherein the ledge is electrically connected to the wiring conductor via brazing metal.

15. (previously presented) The semiconductor light emitting device of claim 13, wherein a lead wire electrically connects the semiconductor light emitting element and a flat area formed in the reflector.

16. (original) A reflector for a semiconductor light emitting device, comprising:

a reflector block mounted on a support plate and formed with a hole for defining a reflective surface upwardly expanding, the reflector block surrounding a semiconductor light emitting element for upwardly reflecting light from the semiconductor light emitting element;

a notch extending through the reflector block from the hole to an outer side surface between the semiconductor light emitting element and wiring conductor; and

a lead wire passing through the notch for electrically connecting the semiconductor light emitting element and wiring conductor.

17. (original) The reflector of claim 16, further comprising a filler received in the notch through which the lead wire extends.

18. (original) The reflector of claim 17, wherein the filler forms a part of the reflector.

19. (currently amended) A semiconductor light emitting device comprising a support plate; a light-reflective reflector having a reflector block which is mounted on the support plate or integrally formed with the support plate, the reflector being formed with a hole upwardly expanding; a semiconductor light emitting element mounted on the support plate within the hole of the reflector; a first wiring conductor electrically connected to one electrode of the light emitting element; a second wiring conductor electrically connected to the other electrode of the light emitting element through a lead wire; ~~and a plastic~~

~~encapsulant for sealing at least the hole of the reflector;~~

wherein the reflector has a notch which passes through the reflector block between the hole and an outer side wall and between the light emitting element and wiring conductor;

the lead wire passes through the notch to electrically connect the light emitting element and wiring conductor.

20. (canceled).

21. (new) The semiconductor light emitting device of claim 1, wherein the plastic encapsulant (6) is formed of black epoxy resin.